

June 2002 Revised June 2002

## FIN1025

## 3.3V LVDS 2-Bit High Speed Differential Driver

### **General Description**

This dual driver is designed for high speed interconnects utilizing Low Voltage Differential Signaling (LVDS) technology. The driver translates LVTTL signal levels to LVDS levels with a typical differential output swing of 350mV which provides low EMI at ultra low power dissipation even at high frequencies. This device is ideal for high speed transfer of clock and data.

The FIN1025 can be paired with its companion receiver, the FIN1026, or any other LVDS receiver.

### **Features**

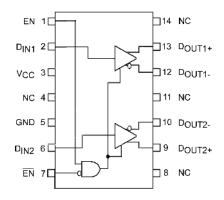
- Greater than 400Mbs data rate
- Flow-through pinout simplifies PCB layout
- 3.3V power supply operation
- 0.4ns maximum differential pulse skew
- 1.7ns maximum propagation delay
- Low power dissipation
- Power-Off protection
- Meets or exceeds the TIA/EIA-644 LVDS standard
- 14-Lead TSSOP package saves space

### **Ordering Code:**

Order Number	Package Number	Package Description
FIN1025MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### **Connection Diagram**



### **Pin Descriptions**

Pin Name	Description
D <sub>IN1</sub> , D <sub>IN2</sub> ,	LVTTL Data Inputs
D <sub>OUT1+</sub> , D <sub>OUT2+</sub>	Non-Inverting Driver Outputs
D <sub>OUT1-</sub> , D <sub>OUT2-</sub>	Inverting Driver Outputs
EN	Driver Enable Pin
EN	Inverting Driver Enable Pin
V <sub>CC</sub>	Power Supply
GND	Ground
NC	No Connect

### **Truth Table**

	Inputs	Outputs			
EN	EN	D <sub>IN</sub>	D <sub>OUT+</sub>	D <sub>OUT</sub>	
Н	L or OPEN	Н	Н	L	
Н	L or OPEN	L	L	Н	
Н	L or OPEN	OPEN	L	Н	
Х	Н	Х	Z	Z	
L or OPEN	Х	Х	Z	Z	

- H = HIGH Logic Level
- L = LOW Logic Level
- X = Don't Care
- Z = High Impedance

## Absolute Maximum Ratings(Note 1)

Storage Temperature Range (T<sub>STG</sub>)

Max Junction Temperature (T<sub>J</sub>)

Lead Temperature (T<sub>L</sub>)
(Soldering, 10 seconds)

ESD (Human Body Model) 10,000V ESD (Machine Model) 600V

# Recommended Operating Conditions

Note 1: The "Absolute Maximum Ratings": are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature and output/input loading variables. Fairchild does not recommend operation of circuits outside databook specification.

### **DC Electrical Characteristics**

Over supply voltage and operating temperature ranges, unless otherwise specified

-65°C to +150°C

150°C

260°C

Symbol	Parameter	Test Conditions	Min	Typ (Note 2)	Max	Units
V <sub>OD</sub>	Output Differential Voltage		250	340	450	mV
$\Delta V_{OD}$	V <sub>OD</sub> Magnitude Change from Differential LOW-to-HIGH	$R_L = 100\Omega$ , Driver Enabled,		1.4	25	mV
Vos	Offset Voltage	See Figure 1	1.125	1.25	1.375	V
ΔV <sub>OS</sub>	Offset Magnitude Change from Differential LOW-to-HIGH			1.2	25	mV
V <sub>OH</sub>	HIGH Output Voltage	$V_{IN} = V_{CC}$ , $R_L = 100\Omega$		1.4	1.6	V
V <sub>OL</sub>	LOW Output Voltage	$V_{IN} = 0V$ , $R_L = 100\Omega$	0.9	1.05		V
l <sub>OFF</sub>	Power Off Output Current	V <sub>CC</sub> = 0V, V <sub>OUT</sub> = 0V or 3.6V	-20		20	μΑ
los	Short Circuit Output Current	V <sub>OUT</sub> = 0V, Driver Enabled		-3	-6	mA
		V <sub>OD</sub> = 0V, Driver Enabled		-3.5	-6	""
V <sub>IH</sub>	Input HIGH Voltage		2.0		V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage		GND		0.8	V
I <sub>IN</sub>	Input Current	$V_{IN} = 0V \text{ or } V_{CC}$	-20		20	μΑ
l <sub>oz</sub>	Disabled Output Leakage Current	V <sub>OUT</sub> = 0V or 3.6V	-20		20	μΑ
I <sub>I(OFF)</sub>	Power-Off Input Current	V <sub>CC</sub> = 0V, V <sub>IN</sub> = 0V or 3.6V	-20		20	μΑ
V <sub>IK</sub>	Input Clamp Voltage	I <sub>IK</sub> = -18 mA	-1.5	-0.8		V
I <sub>CC</sub>	Power Supply Current	No Load, $V_{IN} = 0V$ or $V_{CC}$ , Driver Enabled		5	8	
		$R_L = 100 \Omega$ , Driver Disabled		1.7	4	mA
		$R_L$ = 100 $\Omega,V_{\mbox{\footnotesize{IN}}}$ = 0V or $V_{\mbox{\footnotesize{CC}}},$ Driver Enabled		9	16	

Note 2: All typical values are at  $T_A = 25$ °C and with  $V_{CC} = 3.3$ V.

### **AC Electrical Characteristics**

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ (Note 3)	Max	Units
t <sub>PLHD</sub>	Differential Propagation Delay		0.6	1.1	1.7	ns
	LOW-to-HIGH					
t <sub>PHLD</sub>	Differential Propagation Delay		0.6	1.2	1.7	ns
	HIGH-to-LOW		0.6	1.2	1.7	115
t <sub>TLHD</sub>	Differential Output Rise Time (20% to 80%)	$R_L = 100 \Omega, C_L = 10 pF,$	0.4		1.2	ns
t <sub>THLD</sub>	Differential Output Fall Time (80% to 20%)	See Figure 2 (Note 7), and Figure 3	0.4		1.2	ns
t <sub>SK(P)</sub>	Pulse Skew  t <sub>PLH</sub> - t <sub>PHL</sub>				0.4	ns
t <sub>SK(LH)</sub>	Channel-to-Channel Skew			0.05	0.3	ns
t <sub>SK(HL)</sub>	(Note 4)			0.05	0.5	113
t <sub>SK(PP)</sub>	Part-to-Part Skew (Note 5)				1.0	ns
f <sub>MAX</sub>	Maximum Frequency (Note 6)	$R_L = 100\Omega$ , See Figure 6 (Note 7)	200	250		MHz
t <sub>ZHD</sub>	Differential Output Enable Time from Z to HIGH			1.7	5.0	ns
$t_{ZLD}$	Differential Output Enable Time from Z to LOW	$R_L = 100\Omega, C_L = 10 pF,$		1.7	5.0	ns
t <sub>HZD</sub>	Differential Output Disable Time from HIGH to Z	See Figure 4 (Note 7), and Figure 5		2.7	5.0	ns
t <sub>LZD</sub>	Differential Output Disable Time from LOW to Z	]		2.7	5.0	ns
C <sub>IN</sub>	Input Capacitance			4.2		pF
C <sub>OUT</sub>	Output Capacitance			5.2		pF

Note 3: All typical values are at  $T_A = 25$ °C and with  $V_{CC} = 3.3V$ .

Note 4:  $t_{SK(LH)}$ ,  $t_{SK(HL)}$  is the skew between specified outputs of a single device when the outputs have identical loads and are switching in the same direction.

Note 5: t<sub>SK(PP)</sub> is the magnitude of the difference in propagation delay times between any specified terminals of two devices switching in the same direction (either LOW-to-HIGH or HIGH-to-LOW) when both devices operate with the same supply voltage, same temperature, and have identical test circuits.

 $\textbf{Note 6:} \ \textbf{f}_{MAX} \ \text{criteria: Input} \ \textbf{t}_{R} = \textbf{t}_{F} < \textbf{1ns}, \ \textbf{0V} \ \textbf{to 3V}, \ \textbf{50\%} \ \textbf{Duty Cycle; Output V}_{OD} > \textbf{250 mv}, \ \textbf{45\% to 55\%} \ \textbf{Duty Cycle; all switching in phase channels}.$ 

Note 7: Test Circuits in Figures 2, 4, 6 are simplified representations of test fixture and DUT loading.

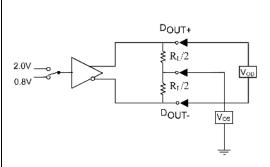
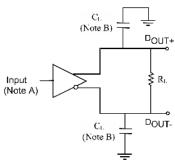


FIGURE 1. Differential Driver DC Test Circuit



 $\label{eq:Note A: All input pulses have frequency = 10 MHz, $t_R$ or $t_F = 1$ ns} \\ \label{eq:Note B: CL} \ \text{includes all fixture and instrumentation capacitance}$ 

FIGURE 2. Differential Driver Propagation Delay and Transition Time Test Circuit

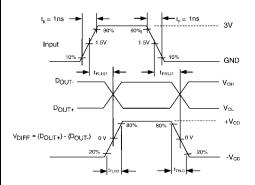
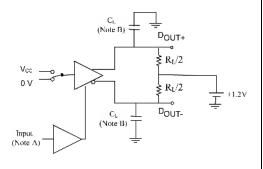


FIGURE 3. AC Waveforms



Note B: All input pulses have the frequency = 10 MHz,  $t_{R}$  or  $t_{F}$  = 1 ns

Note A: C<sub>L</sub> includes all fixture and instrumentation capacitance

FIGURE 4. Differential Driver Enable and Disable Test Circuit

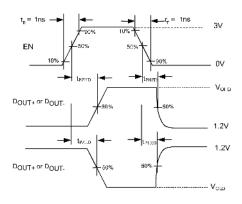


FIGURE 5. Enable and Disable AC Waveforms

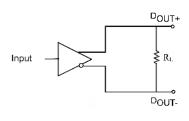
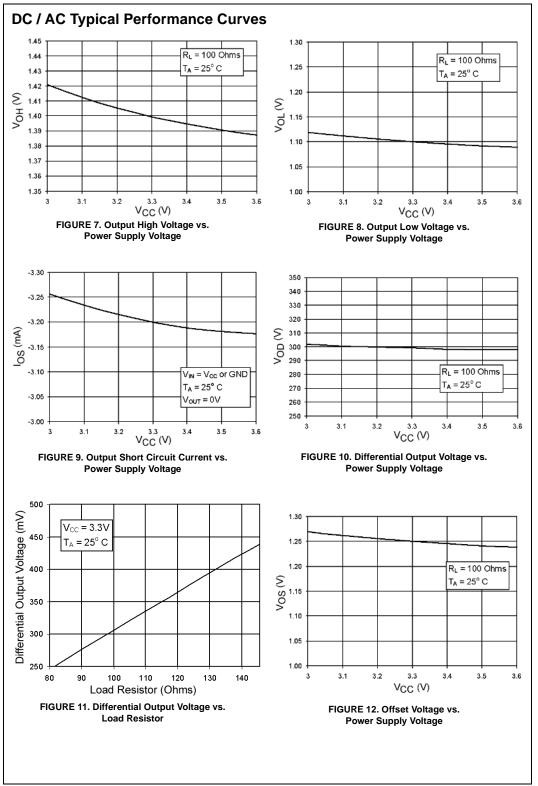


FIGURE 6.  $f_{MAX}$  Test Circuit



## DC / AC Typical Performance Curves (Continued)

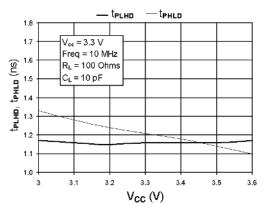


FIGURE 13. Differential Propagation Delay vs. Power Supply Voltage

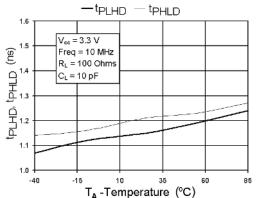


FIGURE 14. Differential Propagation Delay vs.
Ambient Temperature

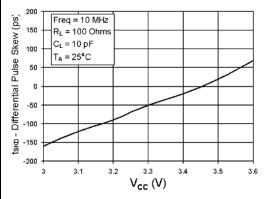


FIGURE 15. Differential Pulse Skew ( $t_{PLH}$  -  $t_{PHL}$ ) vs. Power Supply Voltage

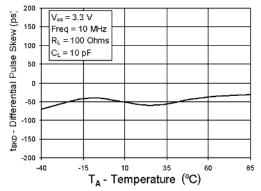
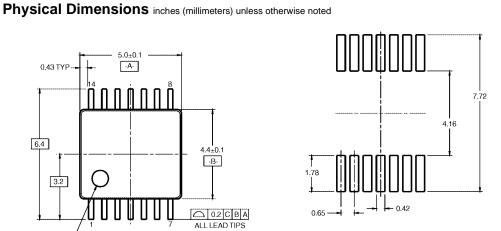
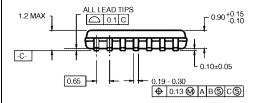


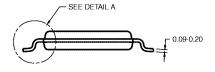
FIGURE 16. Differential Pulse Skew ( $t_{PLH}$  -  $t_{PHL}$ ) vs. Ambient Temperature

## 5.0±0.1 -A-0.43 TYF 6.4 -B-3.2 0.2 C B A ALL LEAD TIPS PIN #1 IDENT.



LAND PATTERN RECOMMENDATION

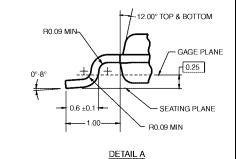




### NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC14RevC3



#### 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

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